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April 1, 2003

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# HM62W16255HCI Series

Wide Temperature Range Version  
4M High Speed SRAM (256-kword × 16-bit)



ADE-203-1263B (Z)

Rev. 2.0  
Dec. 5, 2002

## Description

The HM62W16255HCI is a 4-Mbit high speed static RAM organized 256-kword × 16-bit. It has realized high speed access time by employing CMOS process (6-transistor memory cell) and high speed circuit designing technology. It is most appropriate for the application which requires high speed, high density memory and wide bit width configuration, such as cache and buffer memory in system. The HM62W16255HCI is packaged in 400-mil 44-pin SOJ and 400-mil 44-pin plastic TSOPII for high density surface mounting.

## Features

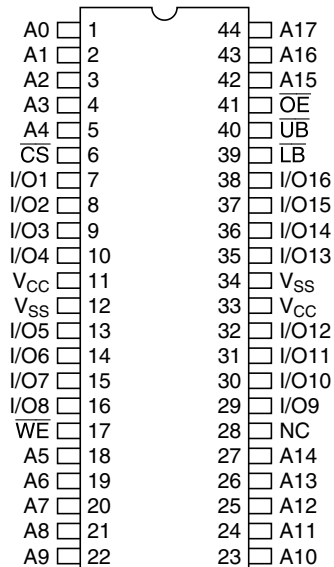
- Single 3.3 V supply: 3.3 V ± 0.3 V
- Access time: 12 ns (max)
- Completely static memory
  - No clock or timing strobe required
- Equal access and cycle times
- Directly TTL compatible
  - All inputs and outputs
- Operating current: 130 mA (max)
- TTL standby current: 40 mA (max)
- CMOS standby current: 5 mA (max)
- Center  $V_{CC}$  and  $V_{SS}$  type pin out
- Temperature range: -40 to +85°C

## Ordering Information

Type No.	Access time	Device marking	Package
HM62W16255HCJPI-12	12 ns	HM62W16255CJPI12	400-mil 44-pin plastic SOJ (CP-44D)
HM62W16255HCTTI-12	12 ns	HM62W16255CTTI12	400-mil 44-pin plastic TSOPII (TTP-44DE)

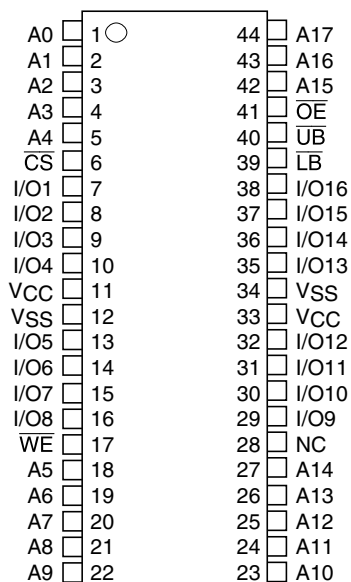
## Pin Arrangement

44-pin SOJ



(Top View)

44-pin TSOP

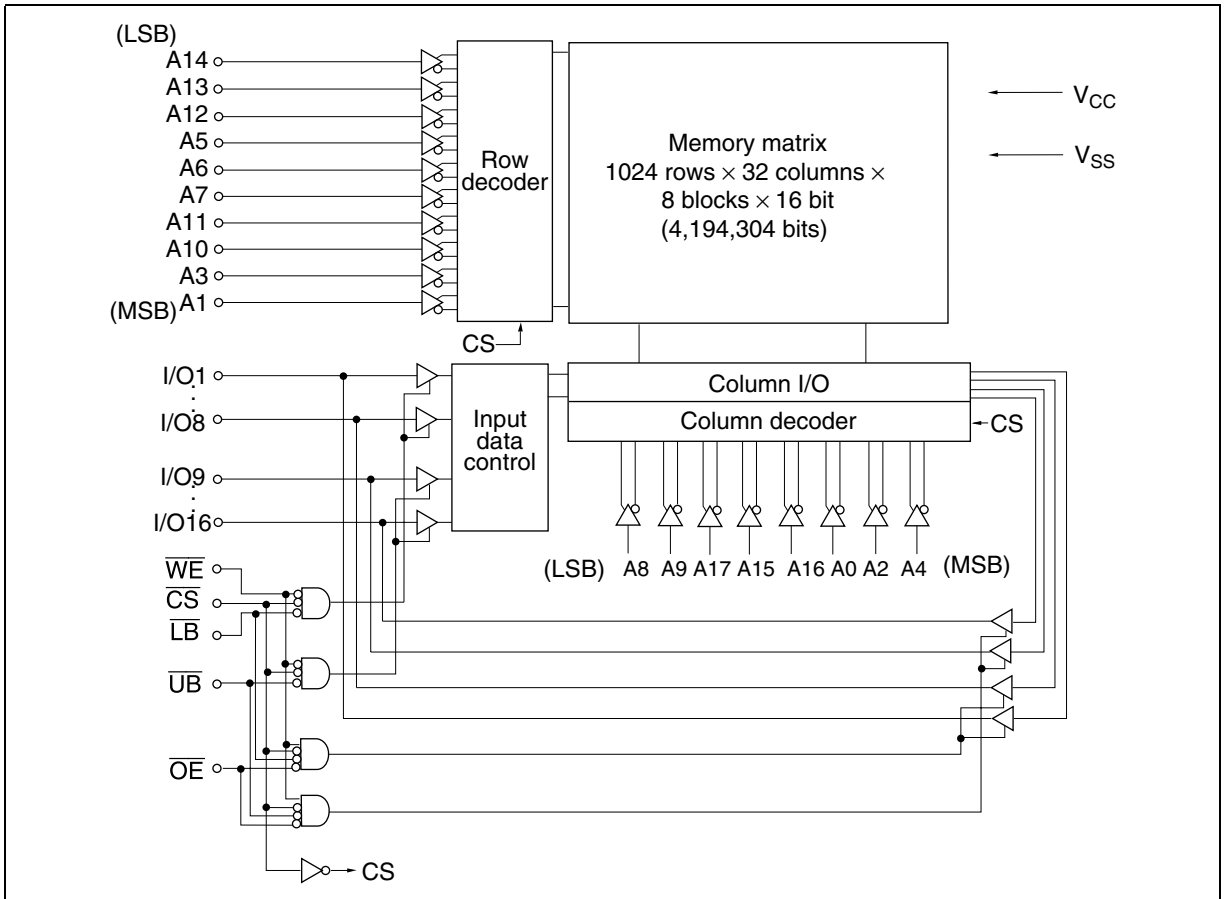


(Top View)

## Pin Description

Pin name	Function
A0 to A17	Address input
I/O1 to I/O16	Data input/output
CS	Chip select
OE	Output enable
WE	Write enable
UB	Upper byte select
LB	Lower byte select
V <sub>cc</sub>	Power supply
V <sub>ss</sub>	Ground
NC	No connection

Block Diagram



## Operation Table

$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	$\overline{LB}$	$\overline{UB}$	Mode	$V_{CC}$ current	I/O1–I/O8	I/O9–I/O16	Ref. Cycle
H	x	x	x	x	Standby	$I_{SB}, I_{SB1}$	High-Z	High-Z	—
L	H	H	x	x	Output disable	$I_{CC}$	High-Z	High-Z	—
L	L	H	L	L	Read	$I_{CC}$	Output	Output	Read cycle
L	L	H	L	H	Lower byte read	$I_{CC}$	Output	High-Z	Read cycle
L	L	H	H	L	Upper byte read	$I_{CC}$	High-Z	Output	Read cycle
L	L	H	H	H	—	$I_{CC}$	High-Z	High-Z	—
L	x	L	L	L	Write	$I_{CC}$	Input	Input	Write cycle
L	x	L	L	H	Lower byte write	$I_{CC}$	Input	High-Z	Write cycle
L	x	L	H	L	Upper byte write	$I_{CC}$	High-Z	Input	Write cycle
L	x	L	H	H	—	$I_{CC}$	High-Z	High-Z	—

Note: H:  $V_{IH}$ , L:  $V_{IL}$ , x:  $V_{IH}$  or  $V_{IL}$

## Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Supply voltage relative to $V_{SS}$	$V_{CC}$	–0.5 to +4.6	V
Voltage on any pin relative to $V_{SS}$	$V_T$	–0.5* <sup>1</sup> to $V_{CC} + 0.5$ * <sup>2</sup>	V
Power dissipation	$P_T$	1.0	W
Operating temperature	$T_{opr}$	–40 to +85	°C
Storage temperature	$T_{stg}$	–55 to +125	°C
Storage temperature under bias	$T_{bias}$	–40 to +85	°C

Notes: 1.  $V_T$  (min) = –2.0 V for pulse width (under shoot)  $\leq 6$  ns

2.  $V_T$  (max) =  $V_{CC} + 2.0$  V for pulse width (over shoot)  $\leq 6$  ns

## Recommended DC Operating Conditions

(Ta = -40 to +85°C)

Parameter	Symbol	Min	Typ	Max	Unit
Supply voltage	$V_{CC}^{*3}$	3.0	3.3	3.6	V
	$V_{SS}^{*4}$	0	0	0	V
Input voltage	$V_{IH}$	2.0	—	$V_{CC} + 0.5^{*2}$	V
	$V_{IL}$	-0.5 <sup>*1</sup>	—	0.8	V

- Notes: 1.  $V_{IL}$  (min) = -2.0 V for pulse width (under shoot) ≤ 6 ns  
 2.  $V_{IH}$  (max) =  $V_{CC} + 2.0$  V for pulse width (over shoot) ≤ 6 ns  
 3. The supply voltage with all  $V_{CC}$  pins must be on the same level.  
 4. The supply voltage with all  $V_{SS}$  pins must be on the same level.

## DC Characteristics

(Ta = -40 to +85°C,  $V_{CC} = 3.3$  V ± 0.3 V,  $V_{SS} = 0$  V)

Parameter	Symbol	Min	Typ <sup>*1</sup>	Max	Unit	Test conditions
Input leakage current	$ I_{LI} $	—	—	2	μA	$V_{IN} = V_{SS}$ to $V_{CC}$
Output leakage current	$ I_{LO} $	—	—	2	μA	$V_{IN} = V_{SS}$ to $V_{CC}$
Operating power supply current	$I_{CC}$	—	—	130	mA	Min cycle $\overline{CS} = V_{IL}$ , $I_{OUT} = 0$ mA Other inputs = $V_{IH}/V_{IL}$
Standby power supply current	$I_{SB}$	—	—	40	mA	Min cycle, $\overline{CS} = V_{IH}$ , Other inputs = $V_{IH}/V_{IL}$
	$I_{SB1}$	—	2.5	5	mA	f = 0 MHz $V_{CC} \geq \overline{CS} \geq V_{CC} - 0.2$ V, (1) $0$ V ≤ $V_{IN}$ ≤ 0.2 V or (2) $V_{CC} \geq V_{IN} \geq V_{CC} - 0.2$ V
Output voltage	$V_{OL}$	—	—	0.4	V	$I_{OL} = 8$ mA
	$V_{OH}$	2.4	—	—	V	$I_{OH} = -4$ mA

- Notes: 1. Typical values are at  $V_{CC} = 3.3$  V, Ta = +25°C and not guaranteed.

# HM62W16255HCI Series

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## Capacitance

(Ta = +25°C, f = 1.0 MHz)

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions
Input capacitance* <sup>1</sup>	C <sub>IN</sub>	—	—	6	pF	V <sub>IN</sub> = 0 V
Input/output capacitance* <sup>1</sup>	C <sub>IO</sub>	—	—	8	pF	V <sub>IO</sub> = 0 V

Note: 1. This parameter is sampled and not 100% tested.

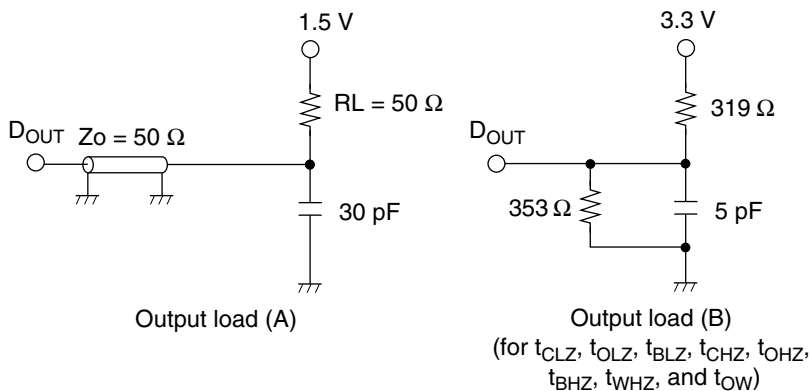


## AC Characteristics

( $T_a = -40$  to  $+85^\circ\text{C}$ ,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ , unless otherwise noted.)

### Test Conditions

- Input pulse levels: 3.0 V/0.0 V
- Input rise and fall time: 3 ns
- Input and output timing reference levels: 1.5 V
- Output load: See figures (Including scope and jig)



### Read Cycle

Parameter	Symbol	HM62W16255HCI		Unit	Notes
		Min	Max		
Read cycle time	$t_{RC}$	12	—	ns	
Address access time	$t_{AA}$	—	12	ns	
Chip select access time	$t_{ACS}$	—	12	ns	
Output enable to output valid	$t_{OE}$	—	6	ns	
Byte select to output valid	$t_{BA}$	—	6	ns	
Output hold from address change	$t_{OH}$	3	—	ns	
Chip select to output in low-Z	$t_{CLZ}$	3	—	ns	1
Output enable to output in low-Z	$t_{OLZ}$	0	—	ns	1
Byte select to output in low-Z	$t_{BLZ}$	0	—	ns	1
Chip deselect to output in high-Z	$t_{CHZ}$	—	6	ns	1
Output disable to output in high-Z	$t_{OHZ}$	—	6	ns	1
Byte deselect to output in high-Z	$t_{BHZ}$	—	6	ns	1

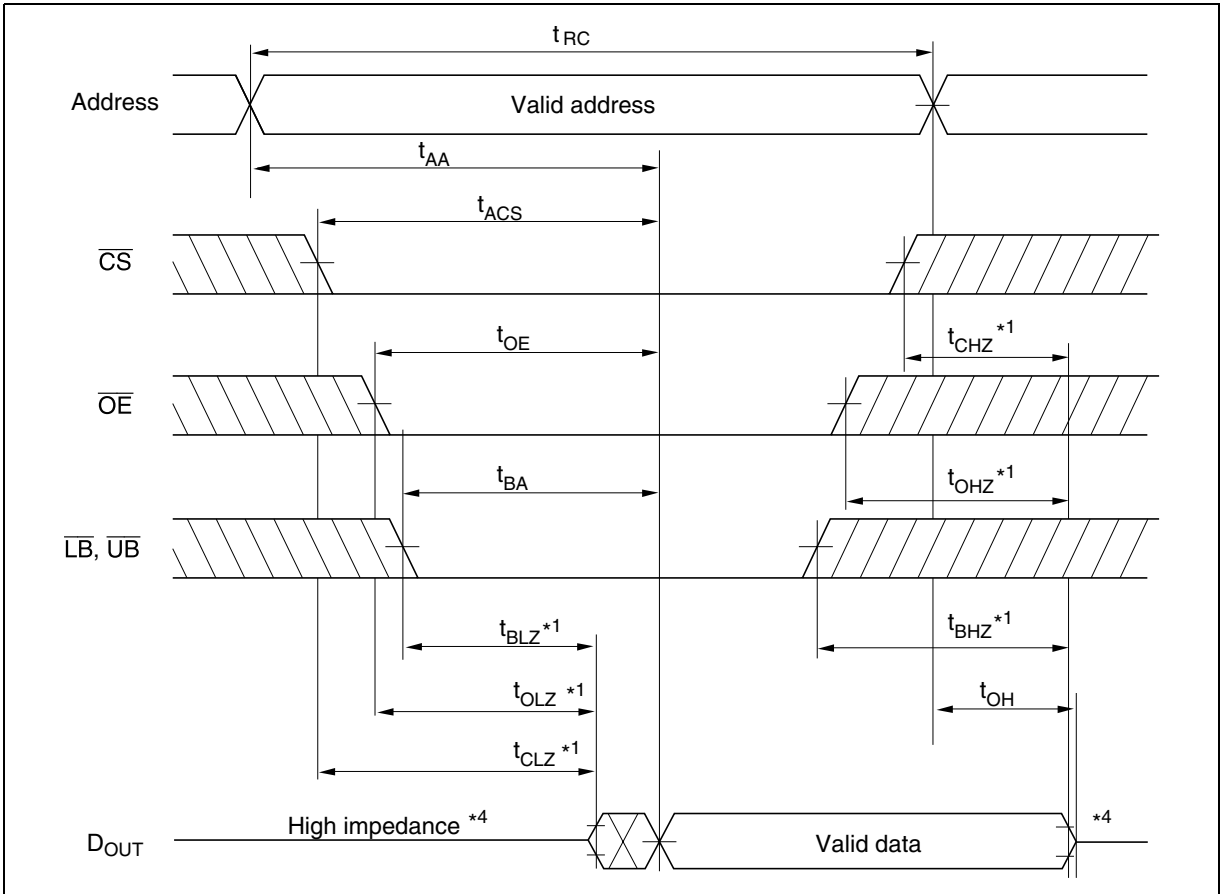
## Write Cycle

Parameter	Symbol	HM62W16255HCI		Unit	Notes
		-12			
		Min	Max		
Write cycle time	$t_{WC}$	12	—	ns	
Address valid to end of write	$t_{AW}$	8	—	ns	
Chip select to end of write	$t_{CW}$	8	—	ns	8
Write pulse width	$t_{WP}$	8	—	ns	7
Byte select to end of write	$t_{BW}$	8	—	ns	
Address setup time	$t_{AS}$	0	—	ns	5
Write recovery time	$t_{WR}$	0	—	ns	6
Data to write time overlap	$t_{DW}$	6	—	ns	
Data hold from write time	$t_{DH}$	0	—	ns	
Write disable to output in low-Z	$t_{OW}$	3	—	ns	1
Output disable to output in high-Z	$t_{OHZ}$	—	6	ns	1
Write enable to output in high-Z	$t_{WHZ}$	—	6	ns	1

- Notes:
1. Transition is measured  $\pm 200$  mV from steady voltage with output load (B). This parameter is sampled and not 100% tested.
  2. If the  $\overline{CS}$  or  $\overline{LB}$  or  $\overline{UB}$  low transition occurs simultaneously with the  $\overline{WE}$  low transition or after the  $\overline{WE}$  transition, output remains a high impedance state.
  3.  $\overline{WE}$  and/or  $\overline{CS}$  must be high during address transition time.
  4. If  $\overline{CS}$ ,  $\overline{OE}$ ,  $\overline{LB}$  and  $\overline{UB}$  are low during this period, I/O pins are in the output state. Then the data input signals of opposite phase to the outputs must not be applied to them.
  5.  $t_{AS}$  is measured from the latest address transition to the latest of  $\overline{CS}$ ,  $\overline{WE}$ ,  $\overline{LB}$  or  $\overline{UB}$  going low.
  6.  $t_{WR}$  is measured from the earliest of  $\overline{CS}$ ,  $\overline{WE}$ ,  $\overline{LB}$  or  $\overline{UB}$  going high to the first address transition.
  7. A write occurs during the overlap of a low  $\overline{CS}$ , a low  $\overline{WE}$  and a low  $\overline{LB}$  or a low  $\overline{UB}$  ( $t_{WP}$ ). A write begins at the latest transition among  $\overline{CS}$  going low,  $\overline{WE}$  going low and  $\overline{LB}$  going low or  $\overline{UB}$  going low. A write ends at the earliest transition among  $\overline{CS}$  going high,  $\overline{WE}$  going high and  $\overline{LB}$  going high or  $\overline{UB}$  going high.
  8.  $t_{CW}$  is measured from the later of  $\overline{CS}$  going low to the end of write.

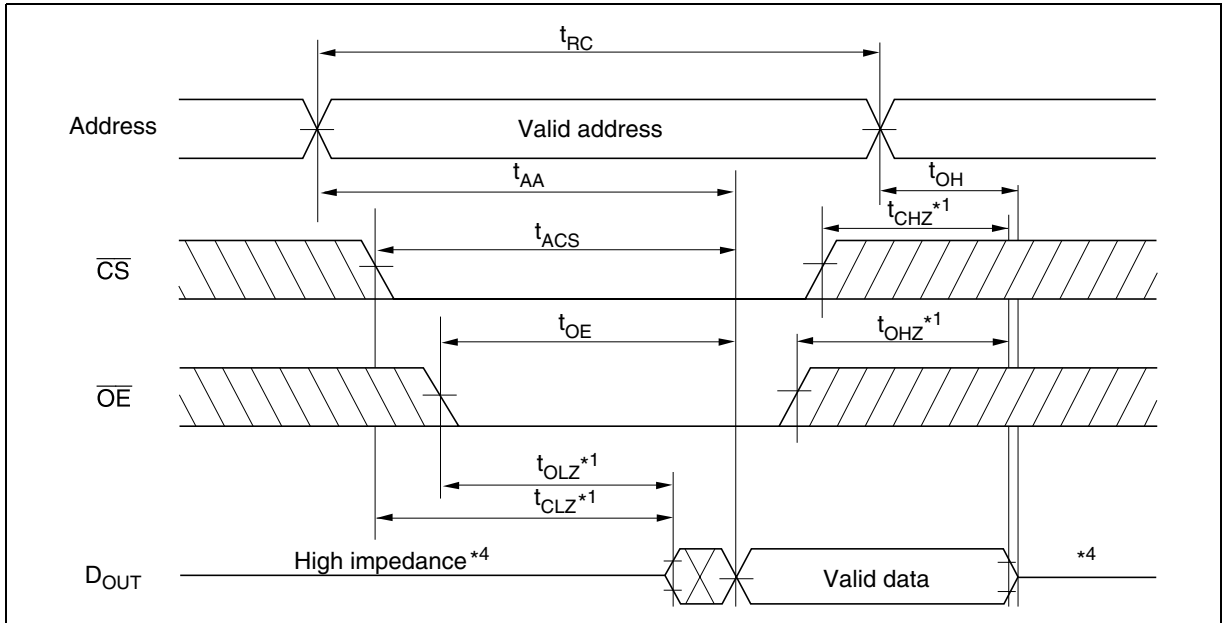
Timing Waveforms

Read Timing Waveform (1) ( $\overline{WE} = V_{IH}$ )

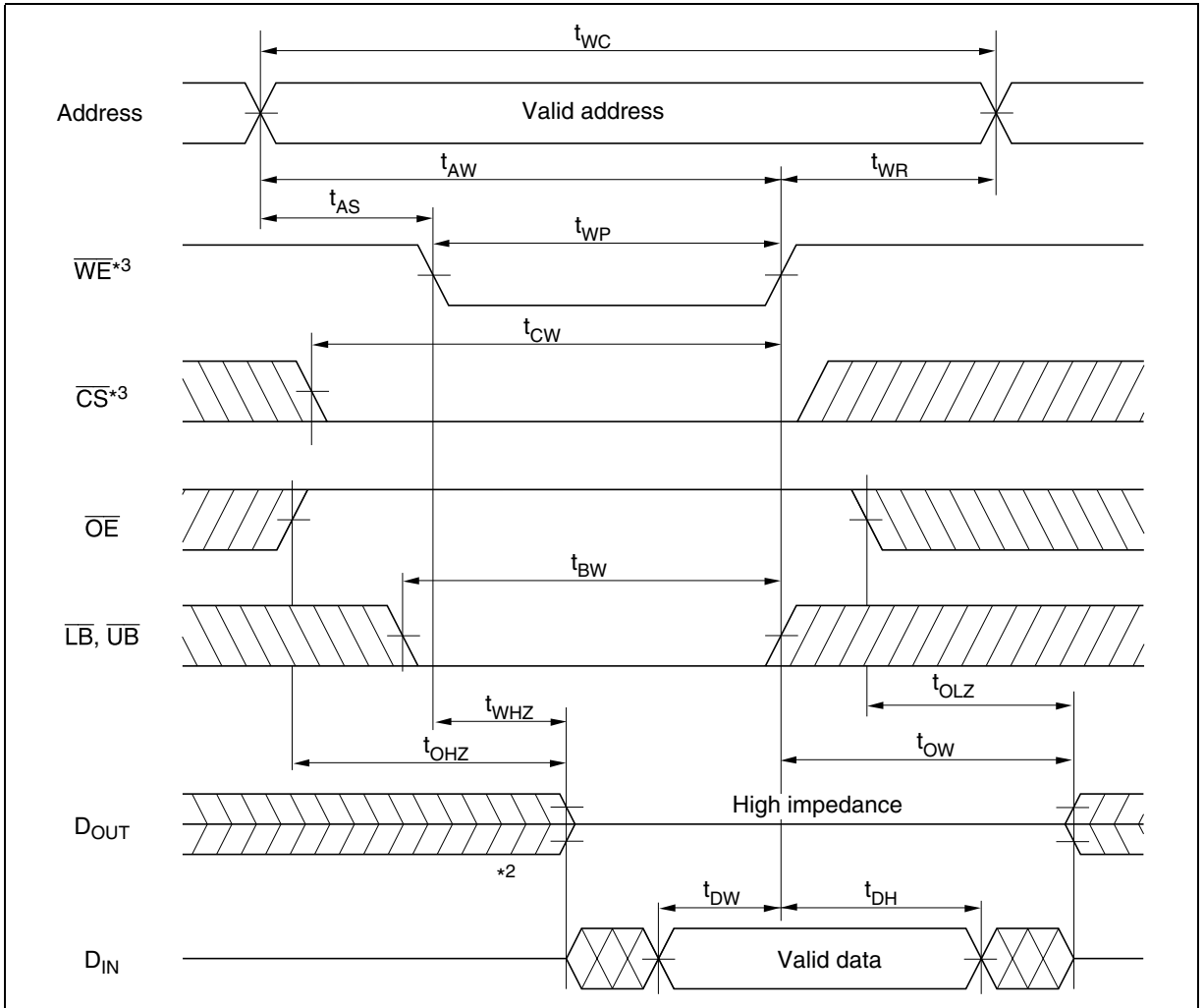


# HM62W16255HCI Series

Read Timing Waveform (2) ( $\overline{WE} = V_{IH}$ ,  $\overline{LB} = V_{IL}$ ,  $\overline{UB} = V_{IL}$ )

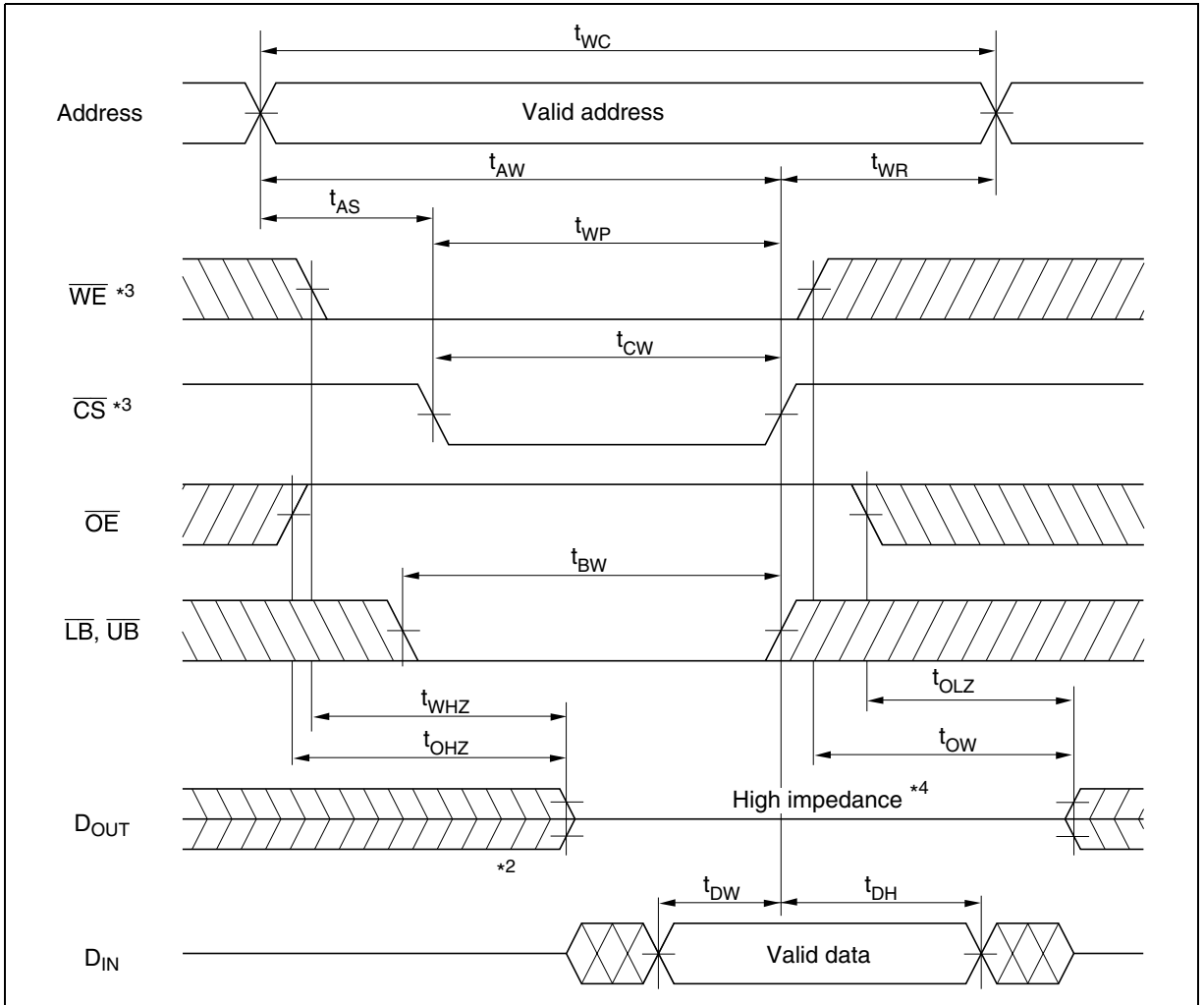


Write Timing Waveform (1) ( $\overline{WE}$  Controlled)

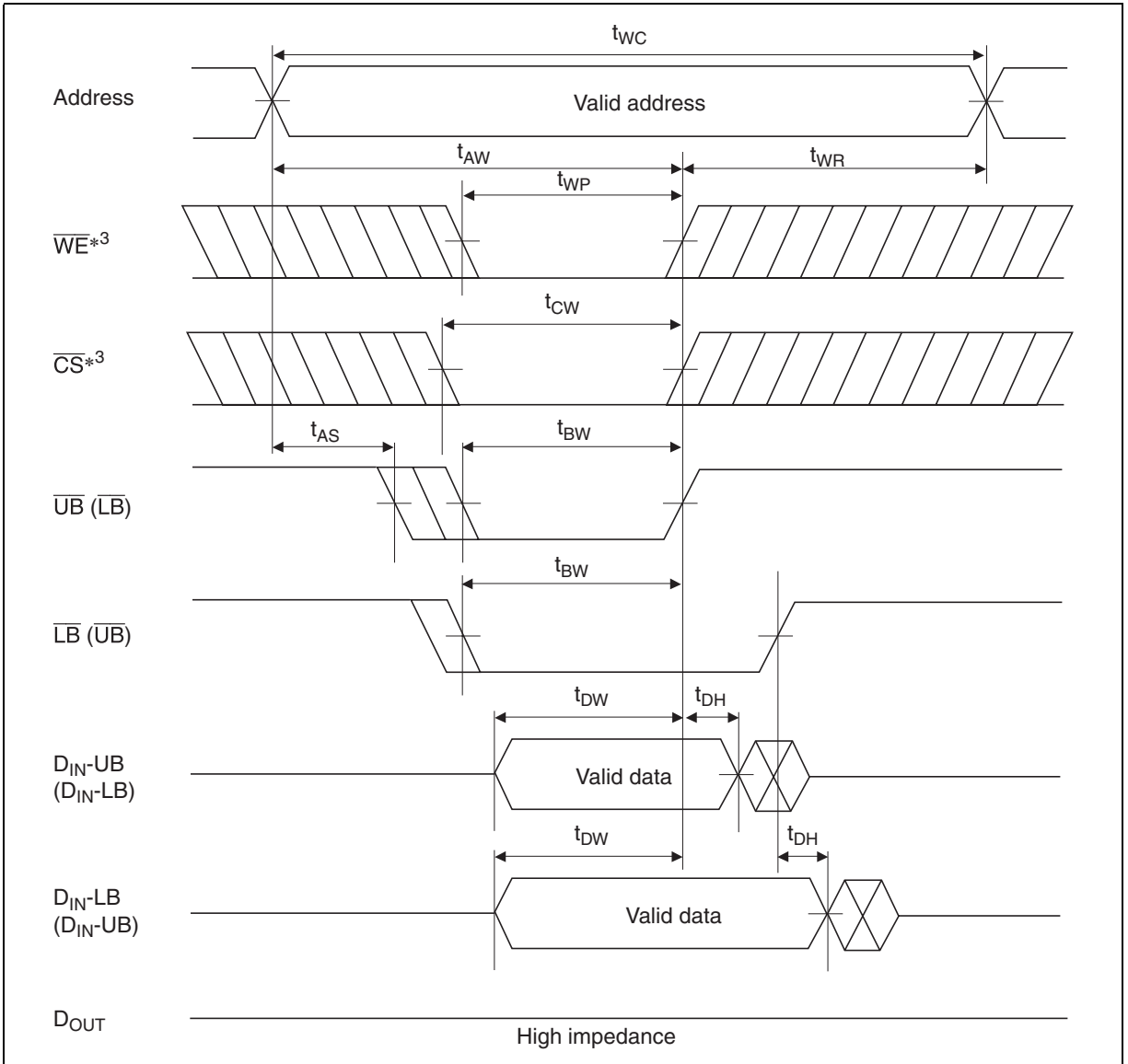


# HM62W16255HCI Series

## Write Timing Waveform (2) ( $\overline{CS}$ Controlled)



Write Timing Waveform (3) ( $\overline{LB}$ ,  $\overline{UB}$  Controlled,  $\overline{OE} = V_{IH}$ )

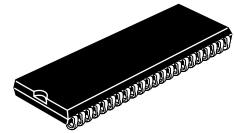
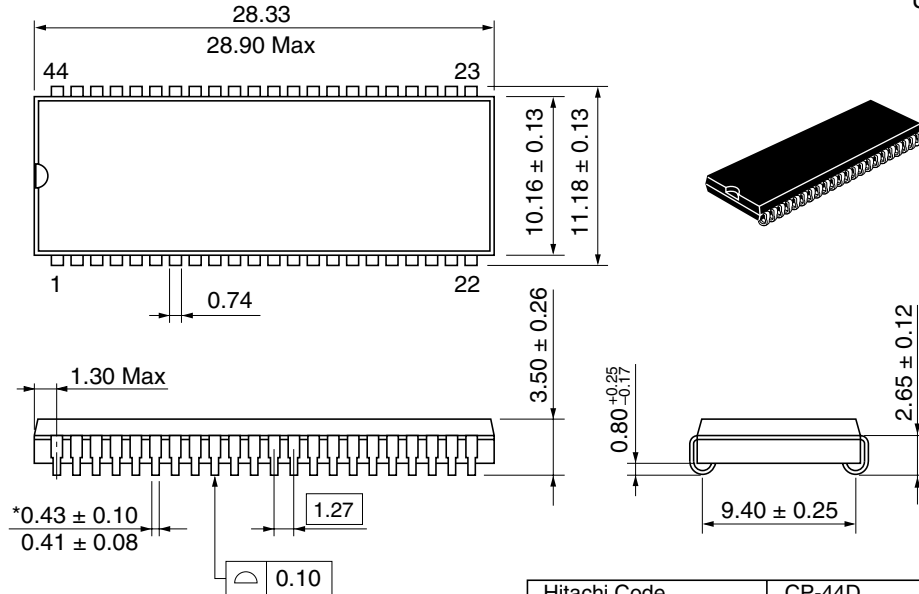


# HM62W16255HCI Series

## Package Dimensions

### HM62W16255HCJPI Series (CP-44D)

As of July, 2002  
Unit: mm



\*Dimension including the plating thickness  
Base material dimension

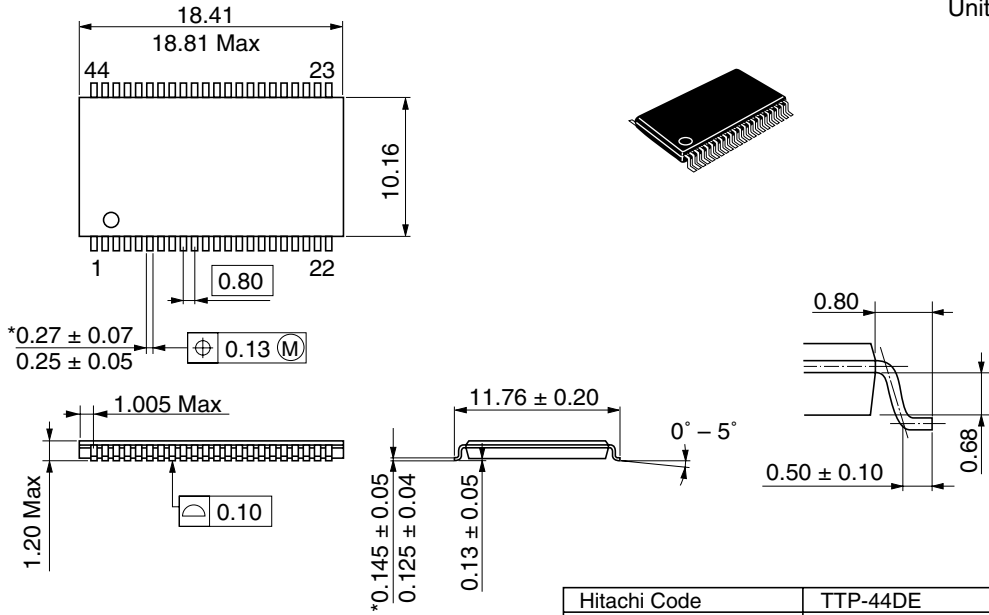
Hitachi Code	CP-44D
JEDEC	Conforms
JEITA	—
Mass (reference value)	1.8 g



## HM62W16255HCTTI Series (TTP-44DE)

As of July, 2002

Unit: mm



\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	TTP-44DE
JEDEC	—
JEITA	—
Mass (reference value)	0.43 g

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